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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Discontinued at Digi-Key
Core Processor	RL78
Core Size	16-Bit
Speed	32MHz
Connectivity	CSI, I <sup>2</sup> C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	31
Program Memory Size	96KB (96K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 10x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	44-LQFP (10x10)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f101ffdfp-v0">https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f101ffdfp-v0</a>

Table 1-1. List of Ordering Part Numbers

(6/12)

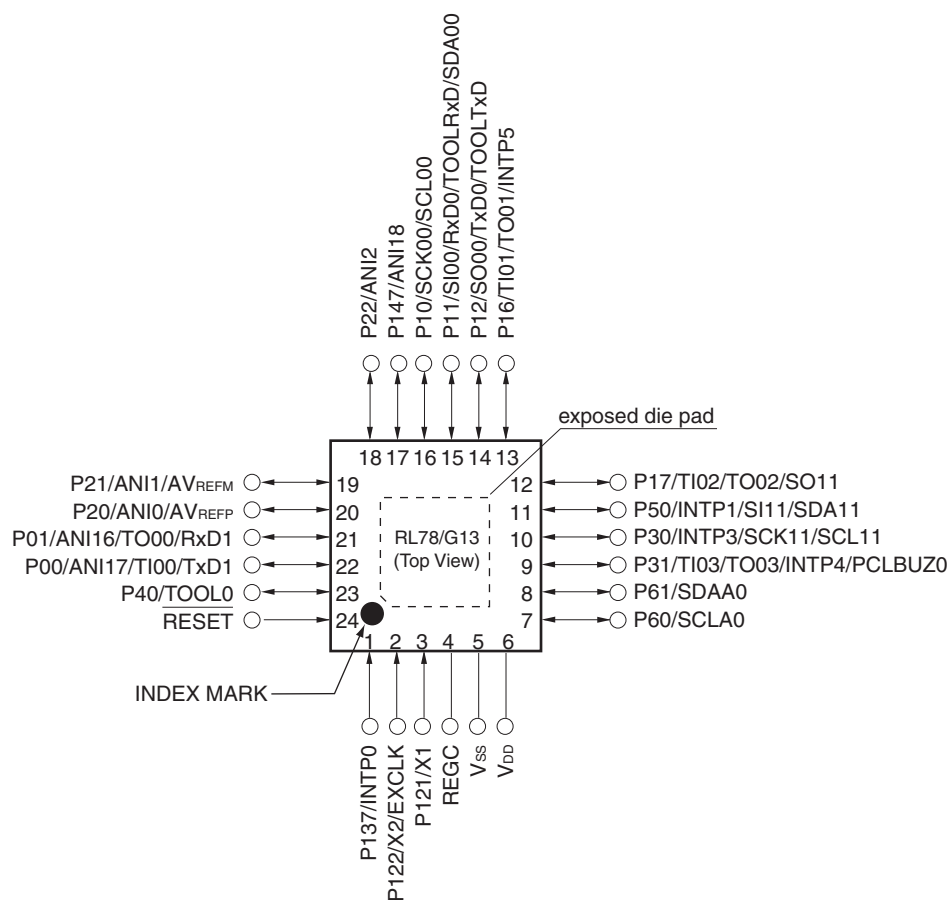
Pin count	Package	Data flash	Fields of Application Note	Ordering Part Number
48 pins	48-pin plastic HWQFN (7 × 7 mm, 0.5 mm pitch)	Mounted	A	R5F100GAANA#U0, R5F100GCANA#U0, R5F100GDANA#U0, R5F100GEANA#U0, R5F100GFANA#U0, R5F100GGANA#U0, R5F100GHANA#U0, R5F100GJANA#U0, R5F100GKANA#U0, R5F100GLANA#U0 R5F100GAANA#W0, R5F100GCANA#W0, R5F100GDANA#W0, R5F100GEANA#W0, R5F100GFANA#W0, R5F100GGANA#W0, R5F100GHANA#W0, R5F100GJANA#W0, R5F100GKANA#W0, R5F100GLANA#W0
		Not mounted	D	R5F100GADNA#U0, R5F100GCDNA#U0, R5F100GDDNA#U0, R5F100GEDNA#U0, R5F100GFDNA#U0, R5F100GGDNA#U0, R5F100GHDNA#U0, R5F100GJDNA#U0, R5F100GKDNA#U0, R5F100GLDNA#U0 R5F100GADNA#W0, R5F100GCDNA#W0, R5F100GDDNA#W0, R5F100GEDNA#W0, R5F100GFDNA#W0, R5F100GGDNA#W0, R5F100GHDNA#W0, R5F100GJDNA#W0, R5F100GKDNA#W0, R5F100GLDNA#W0
			G	R5F100GAGNA#U0, R5F100GCGNA#U0, R5F100GDGNA#U0, R5F100GEGNA#U0, R5F100GFGNA#U0, R5F100GGGNA#U0, R5F100GHGNA#U0, R5F100GJGNA#U0 R5F100GAGNA#W0, R5F100GCGNA#W0, R5F100GDGNA#W0, R5F100GEGNA#W0, R5F100GFGNA#W0, R5F100GGGNA#W0, R5F100GHGNA#W0, R5F100GJGNA#W0
		Not mounted	A	R5F101GAANA#U0, R5F101GCANA#U0, R5F101GDANA#U0, R5F101GEANA#U0, R5F101GFANA#U0, R5F101GGANA#U0, R5F101GHANA#U0, R5F101GJANA#U0, R5F101GKANA#U0, R5F101GLANA#U0 R5F101GAANA#W0, R5F101GCANA#W0, R5F101GDANA#W0, R5F101GEANA#W0, R5F101GFANA#W0, R5F101GGANA#W0, R5F101GHANA#W0, R5F101GJANA#W0, R5F101GKANA#W0, R5F101GLANA#W0
			D	R5F101GADNA#U0, R5F101GCDNA#U0, R5F101GDDNA#U0, R5F101GEDNA#U0, R5F101GFDNA#U0, R5F101GGDNA#U0, R5F101GHDNA#U0, R5F101GJDNA#U0, R5F101GKDNA#U0, R5F101GLDNA#U0 R5F101GADNA#W0, R5F101GCDNA#W0, R5F101GDDNA#W0, R5F101GEDNA#W0, R5F101GFDNA#W0, R5F101GGDNA#W0, R5F101GHDNA#W0, R5F101GJDNA#W0, R5F101GKDNA#W0, R5F101GLDNA#W0

**Note** For the fields of application, refer to **Figure 1-1 Part Number, Memory Size, and Package of RL78/G13**.

**Caution** The ordering part numbers represent the numbers at the time of publication. For the latest ordering part numbers, refer to the target product page of the Renesas Electronics website.

## 1.3.2 24-pin products

- 24-pin plastic HWQFN (4 × 4 mm, 0.5 mm pitch)

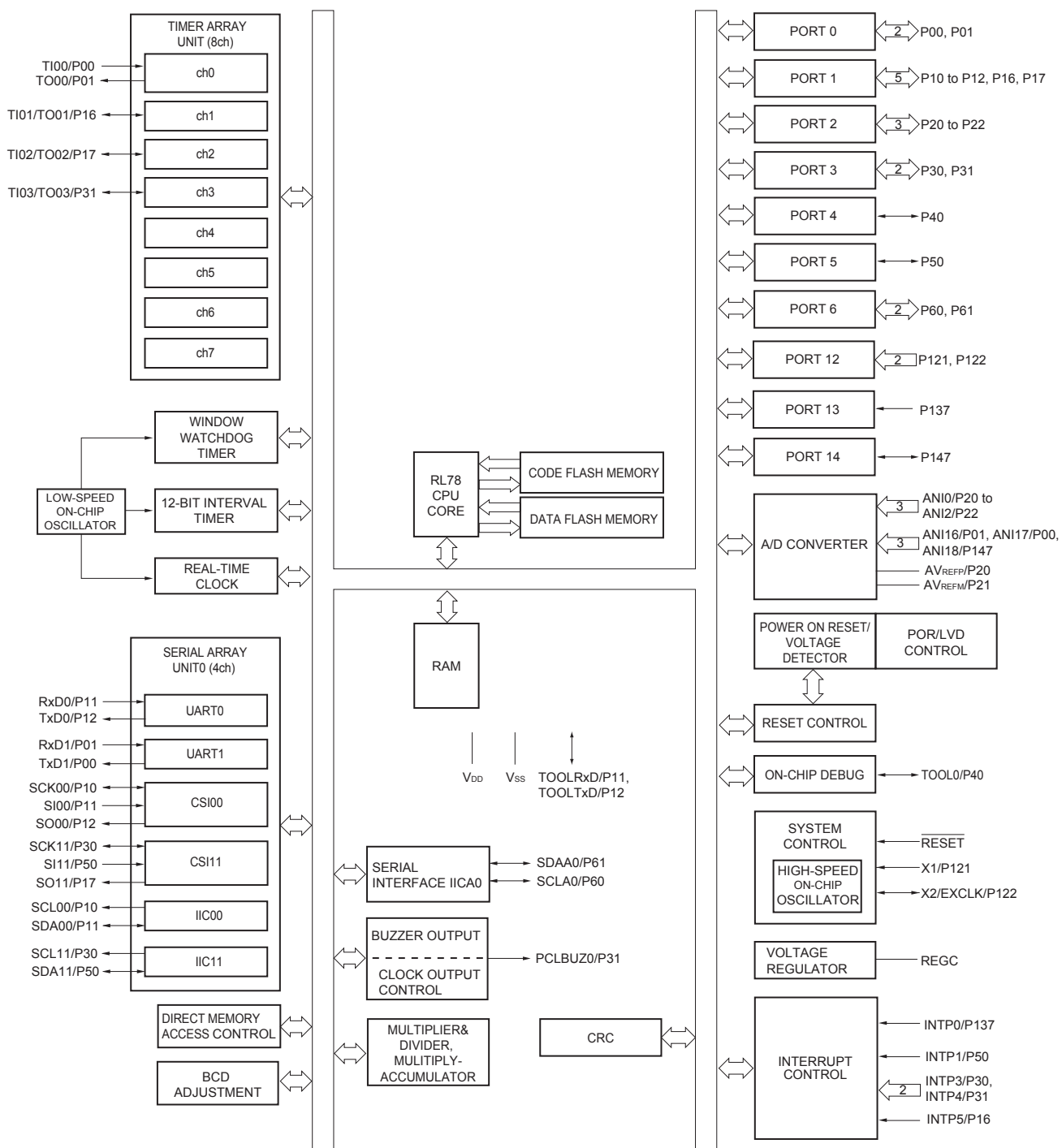


**Caution** Connect the REGC pin to Vss via a capacitor (0.47 to 1  $\mu$ F).

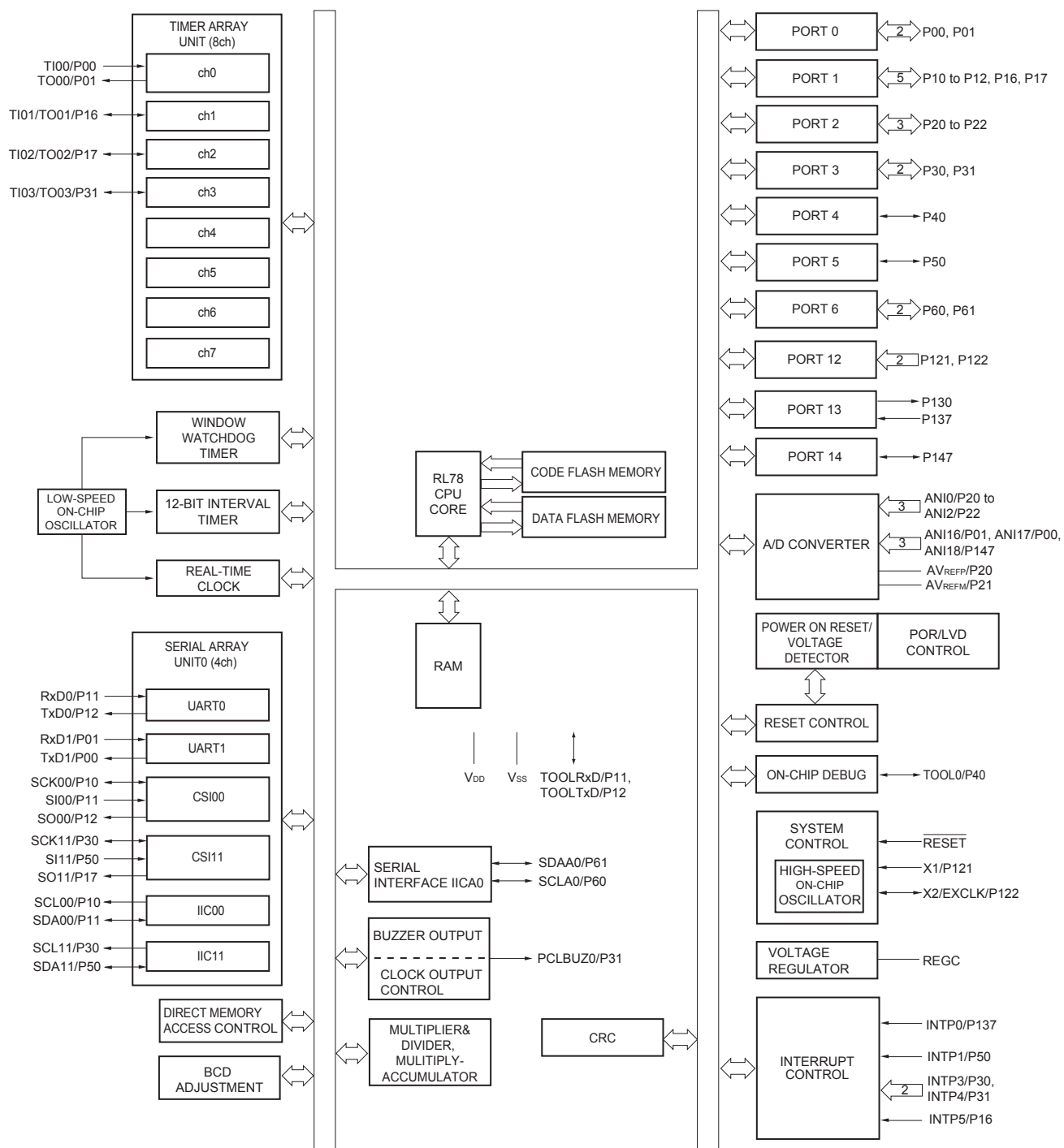
**Remarks** 1. For pin identification, see 1.4 Pin Identification.

2. It is recommended to connect an exposed die pad to Vss.

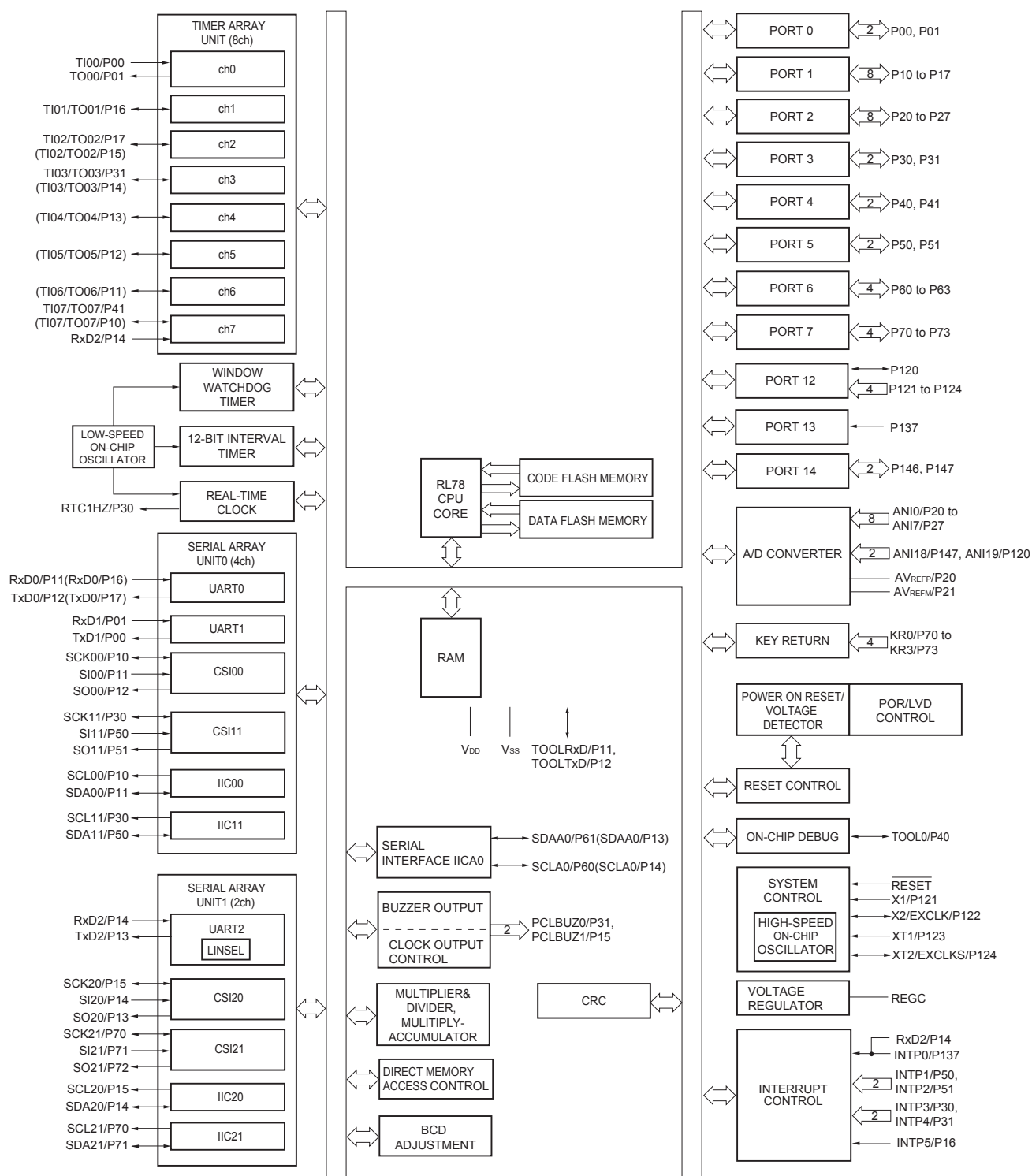
## 1.5.2 24-pin products



## 1.5.3 25-pin products



## 1.5.8 44-pin products



**Remark** Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/G13 User's Manual.

## 1.6 Outline of Functions

[20-pin, 24-pin, 25-pin, 30-pin, 32-pin, 36-pin products]

**Caution** This outline describes the functions at the time when Peripheral I/O redirection register (PIOR) is set to 00H.

(1/2)

Item		20-pin		24-pin		25-pin		30-pin		32-pin		36-pin	
		R5F1006x	R5F1016x	R5F1007x	R5F1017x	R5F1008x	R5F1018x	R5F100Ax	R5F101Ax	R5F100Bx	R5F101Bx	R5F100Cx	R5F101Cx
Code flash memory (KB)		16 to 64		16 to 64		16 to 64		16 to 128		16 to 128		16 to 128	
Data flash memory (KB)		4	–	4	–	4	–	4 to 8	–	4 to 8	–	4 to 8	–
RAM (KB)		2 to 4 <sup>Note1</sup>		2 to 4 <sup>Note1</sup>		2 to 4 <sup>Note1</sup>		2 to 12 <sup>Note1</sup>		2 to 12 <sup>Note1</sup>		2 to 12 <sup>Note1</sup>	
Address space		1 MB											
Main system clock	High-speed system clock	X1 (crystal/ceramic) oscillation, external main system clock input (EXCLK) HS (High-speed main) mode: 1 to 20 MHz (V <sub>DD</sub> = 2.7 to 5.5 V), HS (High-speed main) mode: 1 to 16 MHz (V <sub>DD</sub> = 2.4 to 5.5 V), LS (Low-speed main) mode: 1 to 8 MHz (V <sub>DD</sub> = 1.8 to 5.5 V), LV (Low-voltage main) mode: 1 to 4 MHz (V <sub>DD</sub> = 1.6 to 5.5 V)											
	High-speed on-chip oscillator	HS (High-speed main) mode: 1 to 32 MHz (V <sub>DD</sub> = 2.7 to 5.5 V), HS (High-speed main) mode: 1 to 16 MHz (V <sub>DD</sub> = 2.4 to 5.5 V), LS (Low-speed main) mode: 1 to 8 MHz (V <sub>DD</sub> = 1.8 to 5.5 V), LV (Low-voltage main) mode: 1 to 4 MHz (V <sub>DD</sub> = 1.6 to 5.5 V)											
Subsystem clock		–											
Low-speed on-chip oscillator		15 kHz (TYP.)											
General-purpose registers		(8-bit register × 8) × 4 banks											
Minimum instruction execution time		0.03125 μs (High-speed on-chip oscillator: f <sub>IH</sub> = 32 MHz operation)											
		0.05 μs (High-speed system clock: f <sub>MX</sub> = 20 MHz operation)											
Instruction set		<ul style="list-style-type: none"><li>• Data transfer (8/16 bits)</li><li>• Adder and subtractor/logical operation (8/16 bits)</li><li>• Multiplication (8 bits × 8 bits)</li><li>• Rotate, barrel shift, and bit manipulation (Set, reset, test, and Boolean operation), etc.</li></ul>											
I/O port	Total	16	20	21	26	28	32						
	CMOS I/O	13 (N-ch O.D. I/O [V <sub>DD</sub> withstand voltage]: 5)	15 (N-ch O.D. I/O [V <sub>DD</sub> withstand voltage]: 6)	15 (N-ch O.D. I/O [V <sub>DD</sub> withstand voltage]: 6)	21 (N-ch O.D. I/O [V <sub>DD</sub> withstand voltage]: 9)	22 (N-ch O.D. I/O [V <sub>DD</sub> withstand voltage]: 9)	26 (N-ch O.D. I/O [V <sub>DD</sub> withstand voltage]: 10)						
	CMOS input	3	3	3	3	3	3						
	CMOS output	–	–	1	–	–	–						
	N-ch O.D. I/O (withstand voltage: 6 V)	–	2	2	2	3	3						
Timer	16-bit timer	8 channels											
	Watchdog timer	1 channel											
	Real-time clock (RTC)	1 channel <sup>Note 2</sup>											
	12-bit interval timer (IT)	1 channel											
	Timer output	3 channels (PWM outputs: 2 <sup>Note 3</sup> )	4 channels (PWM outputs: 3 <sup>Note 3</sup> )				4 channels (PWM outputs: 3 <sup>Note 3</sup> ), 8 channels (PWM outputs: 7 <sup>Note 3</sup> ) <sup>Note 4</sup>						
	RTC output	–											

- Notes**
- The flash library uses RAM in self-programming and rewriting of the data flash memory. The target products and start address of the RAM areas used by the flash library are shown below.  
R5F100xD, R5F101xD (x = 6 to 8, A to C): Start address FF300H  
R5F100xE, R5F101xE (x = 6 to 8, A to C): Start address FEF00H  
For the RAM areas used by the flash library, see **Self RAM list of Flash Self-Programming Library for RL78 Family (R20UT2944)**.
  - Only the constant-period interrupt function when the low-speed on-chip oscillator clock (f<sub>IL</sub>) is selected

3. The number of PWM outputs varies depending on the setting of channels in use (the number of masters and slaves) (see **6.9.3 Operation as multiple PWM output function** in the RL78/G13 User's Manual).
4. When setting to PIOR = 1

(2/2)

Item	20-pin		24-pin		25-pin		30-pin		32-pin		36-pin	
	R5F1006x	R5F1016x	R5F1007x	R5F1017x	R5F1008x	R5F1018x	R5F100Ax	R5F101Ax	R5F100Bx	R5F101Bx	R5F100Cx	R5F101Cx
Clock output/buzzer output	—		1		1		2		2		2	
	• 2.44 kHz, 4.88 kHz, 9.76 kHz, 1.25 MHz, 2.5 MHz, 5 MHz, 10 MHz (Main system clock: f <sub>MAIN</sub> = 20 MHz operation)											
8/10-bit resolution A/D converter	6 channels		6 channels		6 channels		8 channels		8 channels		8 channels	
Serial interface	[20-pin, 24-pin, 25-pin products] • CSI: 1 channel/simplified I <sup>2</sup> C: 1 channel/UART: 1 channel • CSI: 1 channel/simplified I <sup>2</sup> C: 1 channel/UART: 1 channel [30-pin, 32-pin products] • CSI: 1 channel/simplified I <sup>2</sup> C: 1 channel/UART: 1 channel • CSI: 1 channel/simplified I <sup>2</sup> C: 1 channel/UART: 1 channel • CSI: 1 channel/simplified I <sup>2</sup> C: 1 channel/UART (UART supporting LIN-bus): 1 channel [36-pin products] • CSI: 1 channel/simplified I <sup>2</sup> C: 1 channel/UART: 1 channel • CSI: 1 channel/simplified I <sup>2</sup> C: 1 channel/UART: 1 channel • CSI: 2 channels/simplified I <sup>2</sup> C: 2 channels/UART (UART supporting LIN-bus): 1 channel											
	I <sup>2</sup> C bus	—	1 channel		1 channel		1 channel		1 channel		1 channel	
Multiplier and divider/multiply-accumulator	• 16 bits × 16 bits = 32 bits (Unsigned or signed) • 32 bits ÷ 32 bits = 32 bits (Unsigned) • 16 bits × 16 bits + 32 bits = 32 bits (Unsigned or signed)											
DMA controller	2 channels											
Vectored interrupt sources	Internal	23	24		24		27		27		27	
	External	3	5		5		6		6		6	
Key interrupt	—											
Reset	• Reset by $\overline{\text{RESET}}$ pin • Internal reset by watchdog timer • Internal reset by power-on-reset • Internal reset by voltage detector • Internal reset by illegal instruction execution <sup>Note</sup> • Internal reset by RAM parity error • Internal reset by illegal-memory access											
Power-on-reset circuit	• Power-on-reset: 1.51 V (TYP.) • Power-down-reset: 1.50 V (TYP.)											
Voltage detector	• Rising edge : 1.67 V to 4.06 V (14 stages) • Falling edge : 1.63 V to 3.98 V (14 stages)											
On-chip debug function	Provided											
Power supply voltage	V <sub>DD</sub> = 1.6 to 5.5 V (T <sub>A</sub> = -40 to +85°C) V <sub>DD</sub> = 2.4 to 5.5 V (T <sub>A</sub> = -40 to +105°C)											
Operating ambient temperature	T <sub>A</sub> = 40 to +85°C (A: Consumer applications, D: Industrial applications ) T <sub>A</sub> = 40 to +105°C (G: Industrial applications)											

**Note** The illegal instruction is generated when instruction code FFH is executed.

Reset by the illegal instruction execution not issued by emulation with the in-circuit emulator or on-chip debug emulator.



## (2) Flash ROM: 96 to 256 KB of 30- to 100-pin products

(T<sub>A</sub> = -40 to +85°C, 1.6 V ≤ E<sub>VDD0</sub> = E<sub>VDD1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = E<sub>VSS0</sub> = E<sub>VSS1</sub> = 0 V) (2/2)

Parameter	Symbol	Conditions				MIN.	TYP.	MAX.	Unit	
Supply current Note 1	I <sub>DD2</sub> Note 2	HALT mode	HS (high-speed main) mode Note 7	f <sub>IH</sub> = 32 MHz <sup>Note 4</sup>	V <sub>DD</sub> = 5.0 V		0.62	1.86	mA	
					V <sub>DD</sub> = 3.0 V		0.62	1.86	mA	
				f <sub>IH</sub> = 24 MHz <sup>Note 4</sup>	V <sub>DD</sub> = 5.0 V		0.50	1.45	mA	
					V <sub>DD</sub> = 3.0 V		0.50	1.45	mA	
				f <sub>IH</sub> = 16 MHz <sup>Note 4</sup>	V <sub>DD</sub> = 5.0 V		0.44	1.11	mA	
					V <sub>DD</sub> = 3.0 V		0.44	1.11	mA	
				LS (low-speed main) mode Note 7	f <sub>IH</sub> = 8 MHz <sup>Note 4</sup>	V <sub>DD</sub> = 3.0 V		290	620	μA
						V <sub>DD</sub> = 2.0 V		290	620	μA
				LV (low-voltage main) mode Note 7	f <sub>IH</sub> = 4 MHz <sup>Note 4</sup>	V <sub>DD</sub> = 3.0 V		440	680	μA
						V <sub>DD</sub> = 2.0 V		440	680	μA
			HS (high-speed main) mode Note 7	f <sub>MX</sub> = 20 MHz <sup>Note 3</sup> , V <sub>DD</sub> = 5.0 V	Square wave input		0.31	1.08	mA	
					Resonator connection		0.48	1.28	mA	
				f <sub>MX</sub> = 20 MHz <sup>Note 3</sup> , V <sub>DD</sub> = 3.0 V	Square wave input		0.31	1.08	mA	
					Resonator connection		0.48	1.28	mA	
				f <sub>MX</sub> = 10 MHz <sup>Note 3</sup> , V <sub>DD</sub> = 5.0 V	Square wave input		0.21	0.63	mA	
					Resonator connection		0.28	0.71	mA	
				f <sub>MX</sub> = 10 MHz <sup>Note 3</sup> , V <sub>DD</sub> = 3.0 V	Square wave input		0.21	0.63	mA	
					Resonator connection		0.28	0.71	mA	
				LS (low-speed main) mode Note 7	f <sub>MX</sub> = 8 MHz <sup>Note 3</sup> , V <sub>DD</sub> = 3.0 V	Square wave input		110	360	μA
						Resonator connection		160	420	μA
			f <sub>MX</sub> = 8 MHz <sup>Note 3</sup> , V <sub>DD</sub> = 2.0 V		Square wave input		110	360	μA	
					Resonator connection		160	420	μA	
			Subsystem clock operation	f <sub>SUB</sub> = 32.768 kHz <sup>Note 5</sup> T <sub>A</sub> = −40°C	Square wave input		0.28	0.61	μA	
					Resonator connection		0.47	0.80	μA	
				f <sub>SUB</sub> = 32.768 kHz <sup>Note 5</sup> T <sub>A</sub> = +25°C	Square wave input		0.34	0.61	μA	
					Resonator connection		0.53	0.80	μA	
				f <sub>SUB</sub> = 32.768 kHz <sup>Note 5</sup> T <sub>A</sub> = +50°C	Square wave input		0.41	2.30	μA	
					Resonator connection		0.60	2.49	μA	
				f <sub>SUB</sub> = 32.768 kHz <sup>Note 5</sup> T <sub>A</sub> = +70°C	Square wave input		0.64	4.03	μA	
					Resonator connection		0.83	4.22	μA	
			f <sub>SUB</sub> = 32.768 kHz <sup>Note 5</sup> T <sub>A</sub> = +85°C	Square wave input		1.09	8.04	μA		
				Resonator connection		1.28	8.23	μA		
	I <sub>DD3</sub> <sup>Note 6</sup>	STOP mode Note 8	T <sub>A</sub> = −40°C					0.19	0.52	μA
			T <sub>A</sub> = +25°C					0.25	0.52	μA
			T <sub>A</sub> = +50°C					0.32	2.21	μA
			T <sub>A</sub> = +70°C					0.55	3.94	μA
			T <sub>A</sub> = +85°C					1.00	7.95	μA

(Notes and Remarks are listed on the next page.)

## 2.4 AC Characteristics

(T<sub>A</sub> = -40 to +85°C, 1.6 V ≤ EV<sub>DD0</sub> = EV<sub>DD1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V)

Items	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Instruction cycle (minimum instruction execution time)	T <sub>CY</sub>	Main system clock (f <sub>MAIN</sub> ) operation	HS (high-speed main) mode	2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V	0.03125	1	μs
				2.4 V ≤ V <sub>DD</sub> < 2.7 V	0.0625	1	μs
			LS (low-speed main) mode	1.8 V ≤ V <sub>DD</sub> ≤ 5.5 V	0.125	1	μs
			LV (low-voltage main) mode	1.6 V ≤ V <sub>DD</sub> ≤ 5.5 V	0.25	1	μs
		Subsystem clock (f <sub>SUB</sub> ) operation		1.8 V ≤ V <sub>DD</sub> ≤ 5.5 V	28.5	30.5	31.3 μs
		In the self programming mode	HS (high-speed main) mode	2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V	0.03125	1	μs
				2.4 V ≤ V <sub>DD</sub> < 2.7 V	0.0625	1	μs
			LS (low-speed main) mode	1.8 V ≤ V <sub>DD</sub> ≤ 5.5 V	0.125	1	μs
			LV (low-voltage main) mode	1.8 V ≤ V <sub>DD</sub> ≤ 5.5 V	0.25	1	μs
External system clock frequency	f <sub>EX</sub>	2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V		1.0		20.0	MHz
		2.4 V ≤ V <sub>DD</sub> < 2.7 V		1.0		16.0	MHz
		1.8 V ≤ V <sub>DD</sub> < 2.4 V		1.0		8.0	MHz
		1.6 V ≤ V <sub>DD</sub> < 1.8 V		1.0		4.0	MHz
	f <sub>EXS</sub>			32		35	kHz
External system clock input high-level width, low-level width	t <sub>EXH</sub> , t <sub>EXL</sub>	2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V		24			ns
		2.4 V ≤ V <sub>DD</sub> < 2.7 V		30			ns
		1.8 V ≤ V <sub>DD</sub> < 2.4 V		60			ns
		1.6 V ≤ V <sub>DD</sub> < 1.8 V		120			ns
	t <sub>EXHS</sub> , t <sub>EXLS</sub>			13.7			μs
Ti00 to Ti07, Ti10 to Ti17 input high-level width, low-level width	t <sub>TIH</sub> , t <sub>TIL</sub>			1/f <sub>MCK</sub> +10			ns <sup>Note</sup>
TO00 to TO07, TO10 to TO17 output frequency	f <sub>TO</sub>	HS (high-speed main) mode		4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		16	MHz
				2.7 V ≤ EV <sub>DD0</sub> < 4.0 V		8	MHz
				1.8 V ≤ EV <sub>DD0</sub> < 2.7 V		4	MHz
				1.6 V ≤ EV <sub>DD0</sub> < 1.8 V		2	MHz
		LS (low-speed main) mode		1.8 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		4	MHz
				1.6 V ≤ EV <sub>DD0</sub> < 1.8 V		2	MHz
		LV (low-voltage main) mode		1.6 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		2	MHz
PCLBUZ0, PCLBUZ1 output frequency	f <sub>PCL</sub>	HS (high-speed main) mode		4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		16	MHz
				2.7 V ≤ EV <sub>DD0</sub> < 4.0 V		8	MHz
				1.8 V ≤ EV <sub>DD0</sub> < 2.7 V		4	MHz
				1.6 V ≤ EV <sub>DD0</sub> < 1.8 V		2	MHz
		LS (low-speed main) mode		1.8 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		4	MHz
				1.6 V ≤ EV <sub>DD0</sub> < 1.8 V		2	MHz
		LV (low-voltage main) mode		1.8 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		4	MHz
				1.6 V ≤ EV <sub>DD0</sub> < 1.8 V		2	MHz
Interrupt input high-level width, low-level width	t <sub>INTH</sub> , t <sub>INTL</sub>	INTP0	1.6 V ≤ V <sub>DD</sub> ≤ 5.5 V	1			μs
		INTP1 to INTP11	1.6 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	1			μs
Key interrupt input low-level width	t <sub>KR</sub>	KR0 to KR7	1.8 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	250			ns
			1.6 V ≤ EV <sub>DD0</sub> < 1.8 V	1			μs
RESET low-level width	t <sub>RSL</sub>			10			μs

(Note and Remark are listed on the next page.)

## (4) During communication at same potential (CSI mode) (slave mode, SCKp... external clock input) (2/2)

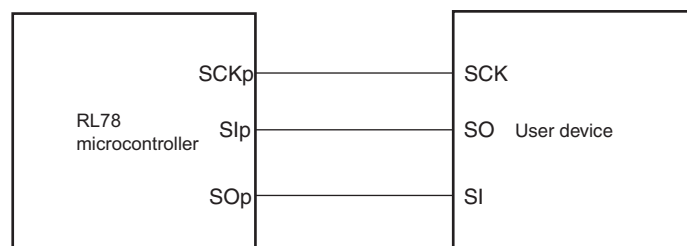
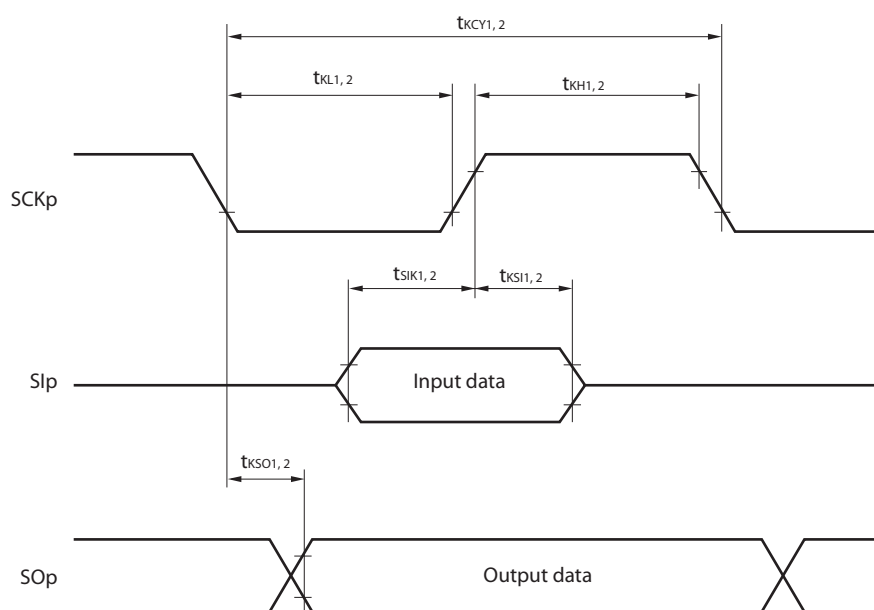
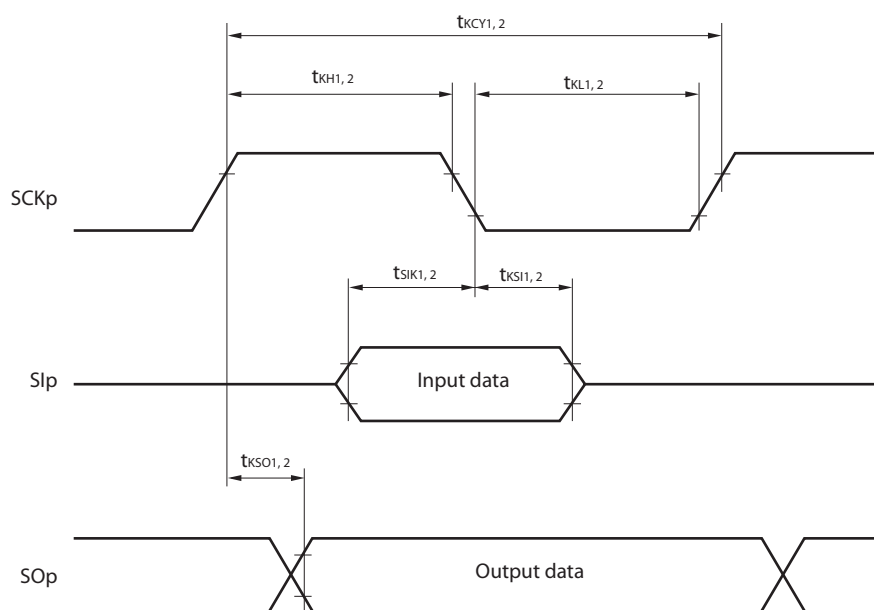
(T<sub>A</sub> = -40 to +85°C, 1.6 V ≤ EV<sub>DD0</sub> = EV<sub>DD1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Slp setup time (to SCKp↑) <sup>Note 1</sup>	t <sub>SIK2</sub>	2.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		1/f <sub>MCK</sub> +20		1/f <sub>MCK</sub> +30		1/f <sub>MCK</sub> +30		ns
		1.8 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		1/f <sub>MCK</sub> +30		1/f <sub>MCK</sub> +30		1/f <sub>MCK</sub> +30		ns
		1.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		1/f <sub>MCK</sub> +40		1/f <sub>MCK</sub> +40		1/f <sub>MCK</sub> +40		ns
		1.6 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		—		1/f <sub>MCK</sub> +40		1/f <sub>MCK</sub> +40		ns
Slp hold time (from SCKp↑) <sup>Note 2</sup>	t <sub>KSI2</sub>	1.8 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		1/f <sub>MCK</sub> +31		1/f <sub>MCK</sub> +31		1/f <sub>MCK</sub> +31		ns
		1.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		1/f <sub>MCK</sub> +250		1/f <sub>MCK</sub> +250		1/f <sub>MCK</sub> +250		ns
		1.6 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		—		1/f <sub>MCK</sub> +250		1/f <sub>MCK</sub> +250		ns
Delay time from SCKp↓ to SOp output <sup>Note 3</sup>	t <sub>KSO2</sub>	C = 30 pF <sup>Note 4</sup>	2.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		2/f <sub>MCK</sub> +44		2/f <sub>MCK</sub> +110		2/f <sub>MCK</sub> +110	ns
			2.4 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		2/f <sub>MCK</sub> +75		2/f <sub>MCK</sub> +110		2/f <sub>MCK</sub> +110	ns
			1.8 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		2/f <sub>MCK</sub> +110		2/f <sub>MCK</sub> +110		2/f <sub>MCK</sub> +110	ns
			1.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		2/f <sub>MCK</sub> +220		2/f <sub>MCK</sub> +220		2/f <sub>MCK</sub> +220	ns
			1.6 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		—		2/f <sub>MCK</sub> +220		2/f <sub>MCK</sub> +220	ns

- Notes**
1. When DAP<sub>mn</sub> = 0 and CKP<sub>mn</sub> = 0, or DAP<sub>mn</sub> = 1 and CKP<sub>mn</sub> = 1. The Slp setup time becomes “to SCKp↓” when DAP<sub>mn</sub> = 0 and CKP<sub>mn</sub> = 1, or DAP<sub>mn</sub> = 1 and CKP<sub>mn</sub> = 0.
  2. When DAP<sub>mn</sub> = 0 and CKP<sub>mn</sub> = 0, or DAP<sub>mn</sub> = 1 and CKP<sub>mn</sub> = 1. The Slp hold time becomes “from SCKp↓” when DAP<sub>mn</sub> = 0 and CKP<sub>mn</sub> = 1, or DAP<sub>mn</sub> = 1 and CKP<sub>mn</sub> = 0.
  3. When DAP<sub>mn</sub> = 0 and CKP<sub>mn</sub> = 0, or DAP<sub>mn</sub> = 1 and CKP<sub>mn</sub> = 1. The delay time to SOp output becomes “from SCKp↑” when DAP<sub>mn</sub> = 0 and CKP<sub>mn</sub> = 1, or DAP<sub>mn</sub> = 1 and CKP<sub>mn</sub> = 0.
  4. C is the load capacitance of the SOp output lines.
  5. Transfer rate in the SNOOZE mode: MAX. 1 Mbps

**Caution** Select the normal input buffer for the Slp pin and SCKp pin and the normal output mode for the SOp pin by using port input mode register g (PIMg) and port output mode register g (POMg).

- Remarks**
1. p: CSI number (p = 00, 01, 10, 11, 20, 21, 30, 31), m: Unit number (m = 0, 1),  
n: Channel number (n = 0 to 3), g: PIM number (g = 0, 1, 4, 5, 8, 14)
  2. f<sub>MCK</sub>: Serial array unit operation clock frequency  
(Operation clock to be set by the CKS<sub>mn</sub> bit of serial mode register mn (SMR<sub>mn</sub>). m: Unit number,  
n: Channel number (mn = 00 to 03, 10 to 13))

**CSI mode connection diagram (during communication at same potential)****CSI mode serial transfer timing (during communication at same potential)  
(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)****CSI mode serial transfer timing (during communication at same potential)  
(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)**

- Remarks**
1. p: CSI number (p = 00, 01, 10, 11, 20, 21, 30, 31)
  2. m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13)

**(6) Communication at different potential (1.8 V, 2.5 V, 3 V) (UART mode) (1/2)****(T<sub>A</sub> = -40 to +85°C, 1.8 V ≤ EV<sub>DD0</sub> = EV<sub>DD1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V)**

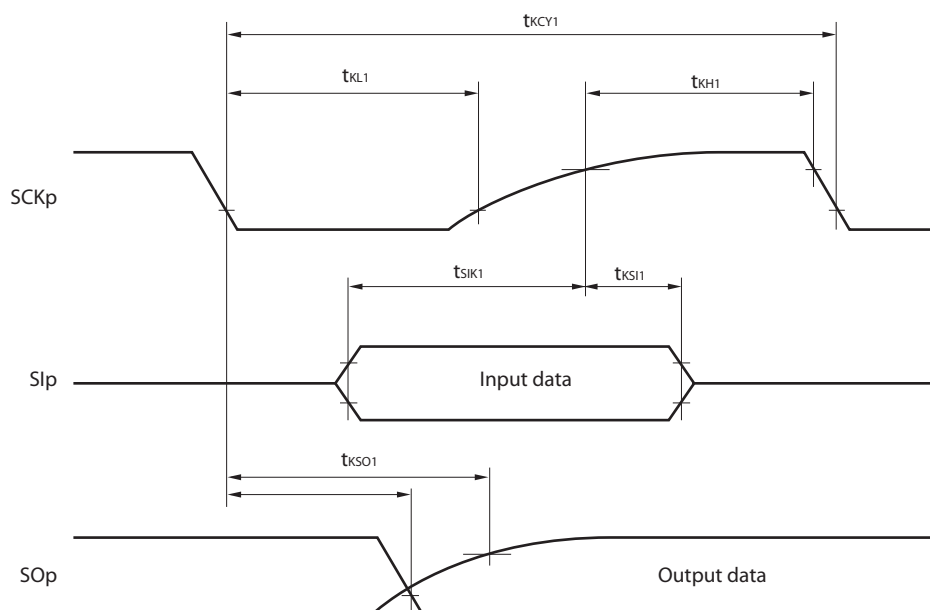
Parameter	Symbol	Conditions		HS (high-speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit	
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Transfer rate		Reception	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, 2.7 V ≤ V <sub>b</sub> ≤ 4.0 V			f <sub>MCK</sub> /6 Note 1		f <sub>MCK</sub> /6 Note 1		f <sub>MCK</sub> /6 Note 1	bps
						5.3		1.3		0.6	Mbps
			Theoretical value of the maximum transfer rate f <sub>MCK</sub> = f <sub>CLK</sub> <sup>Note 4</sup>								
						5.3		1.3		0.6	Mbps
			2.7 V ≤ EV <sub>DD0</sub> < 4.0 V, 2.3 V ≤ V <sub>b</sub> ≤ 2.7 V			f <sub>MCK</sub> /6 Note 1		f <sub>MCK</sub> /6 Note 1		f <sub>MCK</sub> /6 Note 1	bps
						5.3		1.3		0.6	Mbps
1.8 V ≤ EV <sub>DD0</sub> < 3.3 V, 1.6 V ≤ V <sub>b</sub> ≤ 2.0 V			f <sub>MCK</sub> /6 Notes 1 to 3		f <sub>MCK</sub> /6 Notes 1, 2		f <sub>MCK</sub> /6 Notes 1, 2	bps			
			5.3		1.3		0.6	Mbps			
Theoretical value of the maximum transfer rate f <sub>MCK</sub> = f <sub>CLK</sub> <sup>Note 4</sup>											

**Notes 1.** Transfer rate in the SNOOZE mode is 4800 bps only.**2.** Use it with EV<sub>DD0</sub> ≥ V<sub>b</sub>.**3.** The following conditions are required for low voltage interface when EV<sub>DD0</sub> < V<sub>DD</sub>.2.4 V ≤ EV<sub>DD0</sub> < 2.7 V : MAX. 2.6 Mbps1.8 V ≤ EV<sub>DD0</sub> < 2.4 V : MAX. 1.3 Mbps**4.** The maximum operating frequencies of the CPU/peripheral hardware clock (f<sub>CLK</sub>) are:HS (high-speed main) mode: 32 MHz (2.7 V ≤ V<sub>DD</sub> ≤ 5.5 V)16 MHz (2.4 V ≤ V<sub>DD</sub> ≤ 5.5 V)LS (low-speed main) mode: 8 MHz (1.8 V ≤ V<sub>DD</sub> ≤ 5.5 V)LV (low-voltage main) mode: 4 MHz (1.6 V ≤ V<sub>DD</sub> ≤ 5.5 V)

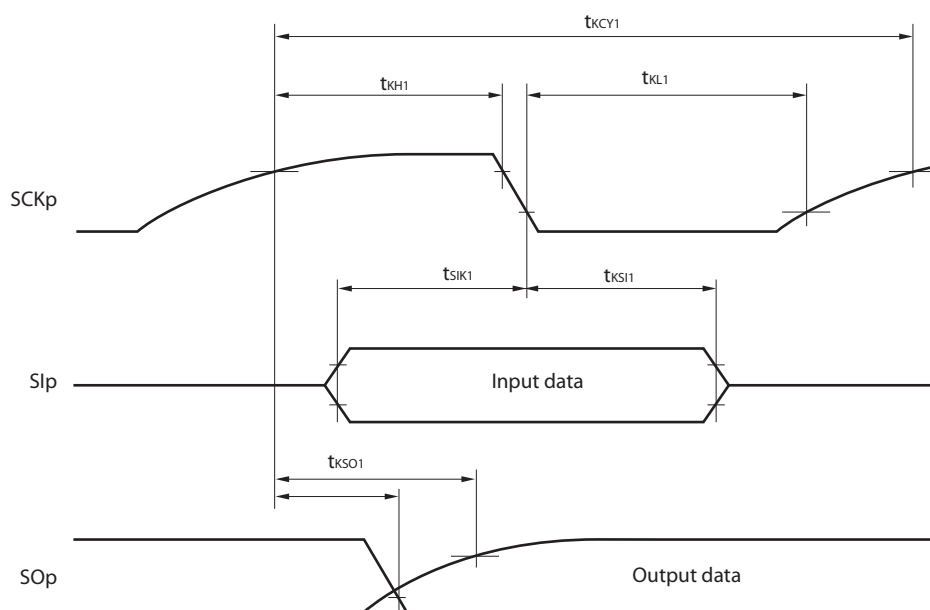
**Caution** Select the TTL input buffer for the RxDq pin and the N-ch open drain output (V<sub>DD</sub> tolerance (When 20- to 52-pin products)/EV<sub>DD</sub> tolerance (When 64- to 128-pin products)) mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V<sub>IH</sub> and V<sub>IL</sub>, see the DC characteristics with TTL input buffer selected.

**Remarks 1.** V<sub>b</sub>[V]: Communication line voltage**2.** q: UART number (q = 0 to 3), g: PIM and POM number (g = 0, 1, 8, 14)**3.** f<sub>MCK</sub>: Serial array unit operation clock frequency(Operation clock to be set by the CKS<sub>mn</sub> bit of serial mode register mn (SMR<sub>mn</sub>). m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13))**4.** UART2 cannot communicate at different potential when bit 1 (PIOR1) of peripheral I/O redirection register (PIOR) is 1.

**CSI mode serial transfer timing (master mode) (during communication at different potential)**  
**(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)**



**CSI mode serial transfer timing (master mode) (during communication at different potential)**  
**(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)**



- Remarks**
1. p: CSI number (p = 00, 01, 10, 20, 30, 31), m: Unit number, n: Channel number (mn = 00, 01, 02, 10, 12, 13), g: PIM and POM number (g = 0, 1, 4, 5, 8, 14)
  2. CSI01 of 48-, 52-, 64-pin products, and CSI11 and CSI21 cannot communicate at different potential. Use other CSI for communication at different potential.

**(9) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (slave mode, SCKp... external clock input)****(T<sub>A</sub> = -40 to +85°C, 1.8 V ≤ EV<sub>DD0</sub> = EV<sub>DD1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V) (2/2)**

Parameter	Symbol	Conditions	HS (high-speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCKp high-/low-level width	t <sub>KH2</sub> , t <sub>KL2</sub>	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, 2.7 V ≤ V <sub>b</sub> ≤ 4.0 V	t <sub>KCY2</sub> /2 - 12		t <sub>KCY2</sub> /2 - 50		t <sub>KCY2</sub> /2 - 50		ns
		2.7 V ≤ EV <sub>DD0</sub> < 4.0 V, 2.3 V ≤ V <sub>b</sub> ≤ 2.7 V	t <sub>KCY2</sub> /2 - 18		t <sub>KCY2</sub> /2 - 50		t <sub>KCY2</sub> /2 - 50		ns
		1.8 V ≤ EV <sub>DD0</sub> < 3.3 V, 1.6 V ≤ V <sub>b</sub> ≤ 2.0 V <sup>Note 2</sup>	t <sub>KCY2</sub> /2 - 50		t <sub>KCY2</sub> /2 - 50		t <sub>KCY2</sub> /2 - 50		ns
Slp setup time (to SCKp↑) <sup>Note 3</sup>	t <sub>SIK2</sub>	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, 2.7 V ≤ V <sub>b</sub> ≤ 4.0 V	1/f <sub>MCK</sub> + 20		1/f <sub>MCK</sub> + 30		1/f <sub>MCK</sub> + 30		ns
		2.7 V ≤ EV <sub>DD0</sub> < 4.0 V, 2.3 V ≤ V <sub>b</sub> ≤ 2.7 V	1/f <sub>MCK</sub> + 20		1/f <sub>MCK</sub> + 30		1/f <sub>MCK</sub> + 30		ns
		1.8 V ≤ EV <sub>DD0</sub> < 3.3 V, 1.6 V ≤ V <sub>b</sub> ≤ 2.0 V <sup>Note 2</sup>	1/f <sub>MCK</sub> + 30		1/f <sub>MCK</sub> + 30		1/f <sub>MCK</sub> + 30		ns
Slp hold time (from SCKp↑) <sup>Note 4</sup>	t <sub>KS12</sub>		1/f <sub>MCK</sub> + 31		1/f <sub>MCK</sub> + 31		1/f <sub>MCK</sub> + 31		ns
Delay time from SCKp↓ to SOp output <sup>Note 5</sup>	t <sub>KSO2</sub>	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, 2.7 V ≤ V <sub>b</sub> ≤ 4.0 V, C <sub>b</sub> = 30 pF, R <sub>b</sub> = 1.4 kΩ		2/f <sub>MCK</sub> + 120		2/f <sub>MCK</sub> + 573		2/f <sub>MCK</sub> + 573	ns
		2.7 V ≤ EV <sub>DD0</sub> < 4.0 V, 2.3 V ≤ V <sub>b</sub> ≤ 2.7 V, C <sub>b</sub> = 30 pF, R <sub>b</sub> = 2.7 kΩ		2/f <sub>MCK</sub> + 214		2/f <sub>MCK</sub> + 573		2/f <sub>MCK</sub> + 573	ns
		1.8 V ≤ EV <sub>DD0</sub> < 3.3 V, 1.6 V ≤ V <sub>b</sub> ≤ 2.0 V <sup>Note 2</sup> , C <sub>b</sub> = 30 pF, R <sub>b</sub> = 5.5 kΩ		2/f <sub>MCK</sub> + 573		2/f <sub>MCK</sub> + 573		2/f <sub>MCK</sub> + 573	ns

**Notes** 1. Transfer rate in the SNOOZE mode : MAX. 1 Mbps2. Use it with EV<sub>DD0</sub> ≥ V<sub>b</sub>.

3. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The Slp setup time becomes “to SCKp↓” when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

4. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The Slp hold time becomes “from SCKp↓” when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

5. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes “from SCKp↑” when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

**Caution** Select the TTL input buffer for the Slp pin and the N-ch open drain output (V<sub>DD</sub> tolerance (for the 20- to 52-pin products)/EV<sub>DD</sub> tolerance (for the 64- to 128-pin products)) mode for the SOp pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V<sub>IH</sub> and V<sub>IL</sub>, see the DC characteristics with TTL input buffer selected.

(Remarks are listed on the next page.)

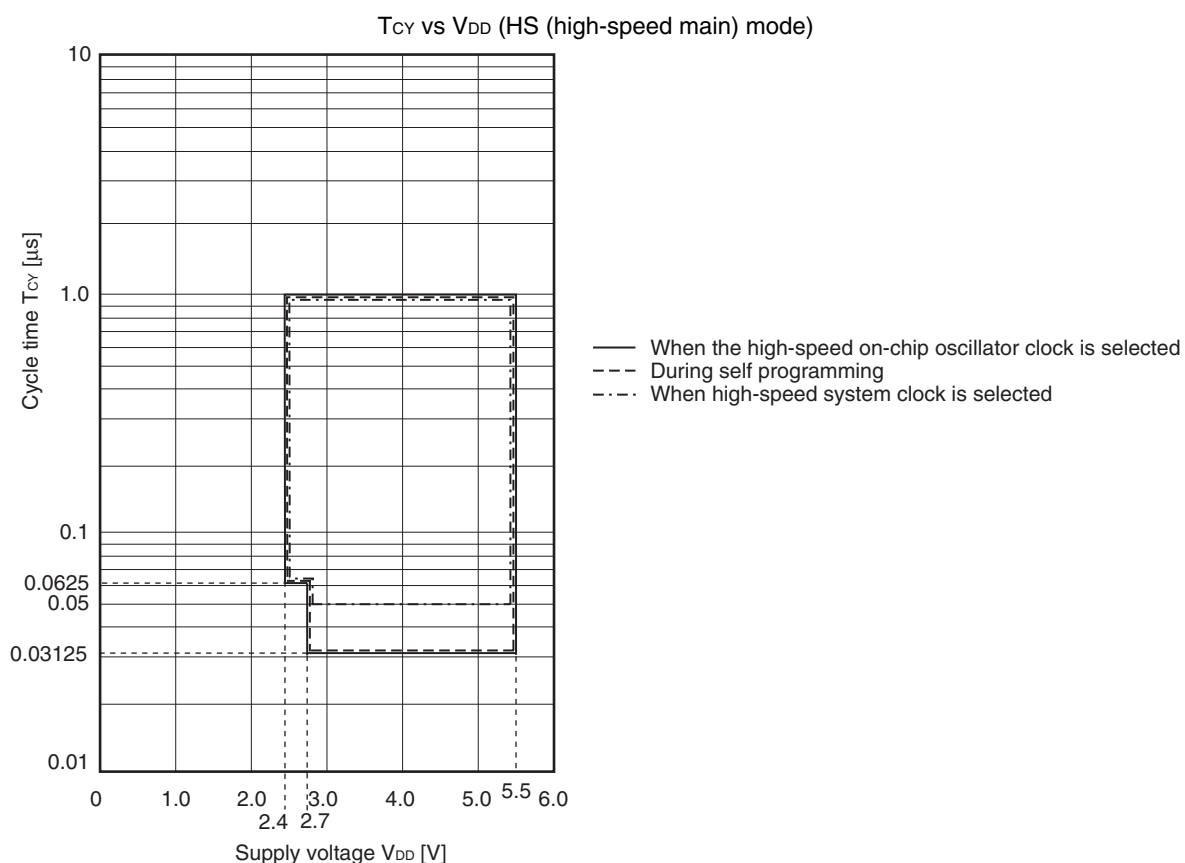
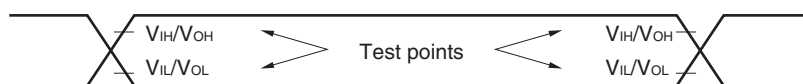
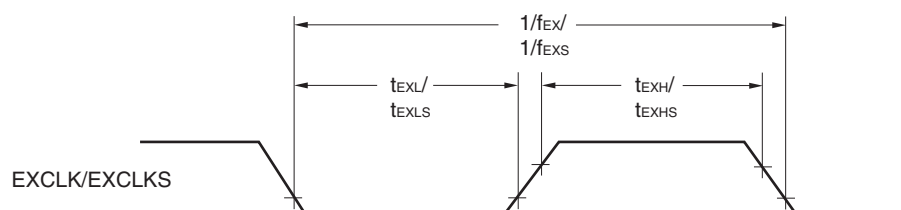
**Absolute Maximum Ratings ( $T_A = 25^{\circ}\text{C}$ ) (2/2)**

Parameter	Symbols	Conditions		Ratings	Unit
Output current, high	I <sub>OH1</sub>	Per pin	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P130, P140 to P147	−40	mA
		Total of all pins −170 mA	P00 to P04, P07, P32 to P37, P40 to P47, P102 to P106, P120, P125 to P127, P130, P140 to P145	−70	mA
			P05, P06, P10 to P17, P30, P31, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100, P101, P110 to P117, P146, P147	−100	mA
	I <sub>OH2</sub>	Per pin	P20 to P27, P150 to P156	−0.5	mA
		Total of all pins		−2	mA
Output current, low	I <sub>OL1</sub>	Per pin	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P130, P140 to P147	40	mA
		Total of all pins 170 mA	P00 to P04, P07, P32 to P37, P40 to P47, P102 to P106, P120, P125 to P127, P130, P140 to P145	70	mA
			P05, P06, P10 to P17, P30, P31, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P97, P100, P101, P110 to P117, P146, P147	100	mA
	I <sub>OL2</sub>	Per pin	P20 to P27, P150 to P156	1	mA
		Total of all pins		5	mA
Operating ambient temperature	T <sub>A</sub>	In normal operation mode		−40 to +105	°C
		In flash memory programming mode			
Storage temperature	T <sub>stg</sub>			−65 to +150	°C

**Caution** Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

**Remark** Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.



**Minimum Instruction Execution Time during Main System Clock Operation****AC Timing Test Points****External System Clock Timing**

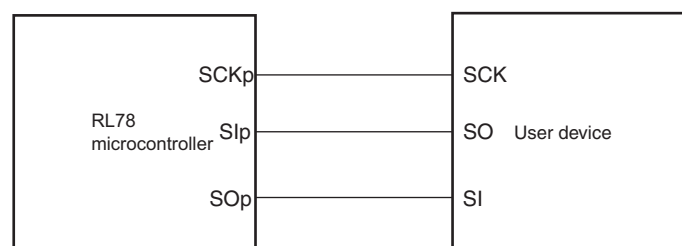
**(3) During communication at same potential (CSI mode) (slave mode, SCKp... external clock input)****( $T_A = -40$  to  $+105^{\circ}\text{C}$ ,  $2.4\text{ V} \leq \text{EV}_{\text{DD0}} = \text{EV}_{\text{DD1}} \leq \text{V}_{\text{DD}} \leq 5.5\text{ V}$ ,  $\text{V}_{\text{SS}} = \text{EV}_{\text{SS0}} = \text{EV}_{\text{SS1}} = 0\text{ V}$ )**

Parameter	Symbol	Conditions		HS (high-speed main) Mode		Unit
				MIN.	MAX.	
SCKp cycle time <sup>Note 5</sup>	t <sub>KCY2</sub>	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	20 MHz < f <sub>MCK</sub>	16/f <sub>MCK</sub>		ns
			f <sub>MCK</sub> ≤ 20 MHz	12/f <sub>MCK</sub>		ns
		2.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	16 MHz < f <sub>MCK</sub>	16/f <sub>MCK</sub>		ns
			f <sub>MCK</sub> ≤ 16 MHz	12/f <sub>MCK</sub>		ns
		2.4 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		16/f <sub>MCK</sub>		ns
				12/f <sub>MCK</sub> and 1000		ns
SCKp high-/low-level width	t <sub>KH2</sub> , t <sub>KL2</sub>	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		t <sub>KCY2</sub> /2 – 14		ns
		2.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		t <sub>KCY2</sub> /2 – 16		ns
		2.4 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		t <sub>KCY2</sub> /2 – 36		ns
Slp setup time (to SCKp↑) <sup>Note 1</sup>	t <sub>SIK2</sub>	2.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		1/f <sub>MCK</sub> +40		ns
		2.4 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		1/f <sub>MCK</sub> +60		ns
Slp hold time (from SCKp↑) <sup>Note 2</sup>	t <sub>KSI2</sub>	2.4 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		1/f <sub>MCK</sub> +62		ns
Delay time from SCKp↓ to SOp output <sup>Note 3</sup>	t <sub>KSO2</sub>	C = 30 pF <sup>Note 4</sup>	2.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		2/f <sub>MCK</sub> +66	ns
			2.4 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		2/f <sub>MCK</sub> +113	ns

- Notes**
1. When  $\text{DAPmn} = 0$  and  $\text{CKPmn} = 0$ , or  $\text{DAPmn} = 1$  and  $\text{CKPmn} = 1$ . The Slp setup time becomes “to SCKp $\downarrow$ ” when  $\text{DAPmn} = 0$  and  $\text{CKPmn} = 1$ , or  $\text{DAPmn} = 1$  and  $\text{CKPmn} = 0$ .
  2. When  $\text{DAPmn} = 0$  and  $\text{CKPmn} = 0$ , or  $\text{DAPmn} = 1$  and  $\text{CKPmn} = 1$ . The Slp hold time becomes “from SCKp $\downarrow$ ” when  $\text{DAPmn} = 0$  and  $\text{CKPmn} = 1$ , or  $\text{DAPmn} = 1$  and  $\text{CKPmn} = 0$ .
  3. When  $\text{DAPmn} = 0$  and  $\text{CKPmn} = 0$ , or  $\text{DAPmn} = 1$  and  $\text{CKPmn} = 1$ . The delay time to SOp output becomes “from SCKp $\uparrow$ ” when  $\text{DAPmn} = 0$  and  $\text{CKPmn} = 1$ , or  $\text{DAPmn} = 1$  and  $\text{CKPmn} = 0$ .
  4. C is the load capacitance of the SOp output lines.
  5. Transfer rate in the SNOOZE mode : MAX. 1 Mbps

**Caution** Select the normal input buffer for the Slp pin and SCKp pin and the normal output mode for the SOp pin by using port input mode register g (PIMg) and port output mode register g (POMg).

- Remarks**
1. p: CSI number (p = 00, 01, 10, 11, 20, 21, 30, 31), m: Unit number (m = 0, 1),  
n: Channel number (n = 0 to 3), g: PIM number (g = 0, 1, 4, 5, 8, 14)
  2.  $f_{\text{MCK}}$ : Serial array unit operation clock frequency  
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number,  
n: Channel number (mn = 00 to 03, 10 to 13))

**CSI mode connection diagram (during communication at same potential)**

**(6) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (master mode, SCKp... internal clock output) (2/3)****( $T_A = -40$  to  $+105^\circ\text{C}$ ,  $2.4\text{ V} \leq \text{EV}_{\text{DD}0} = \text{EV}_{\text{DD}1} \leq \text{V}_{\text{DD}} \leq 5.5\text{ V}$ ,  $\text{V}_{\text{SS}} = \text{EV}_{\text{SS}0} = \text{EV}_{\text{SS}1} = 0\text{ V}$ )**

Parameter	Symbol	Conditions	HS (high-speed main) Mode		Unit
			MIN.	MAX.	
Slp setup time (to SCKp $\uparrow$ ) <sup>Note</sup>	$t_{\text{SIK}1}$	$4.0\text{ V} \leq \text{EV}_{\text{DD}0} \leq 5.5\text{ V}$ , $2.7\text{ V} \leq \text{V}_b \leq 4.0\text{ V}$ , $\text{C}_b = 30\text{ pF}$ , $\text{R}_b = 1.4\text{ k}\Omega$	162		ns
		$2.7\text{ V} \leq \text{EV}_{\text{DD}0} < 4.0\text{ V}$ , $2.3\text{ V} \leq \text{V}_b \leq 2.7\text{ V}$ , $\text{C}_b = 30\text{ pF}$ , $\text{R}_b = 2.7\text{ k}\Omega$	354		ns
		$2.4\text{ V} \leq \text{EV}_{\text{DD}0} < 3.3\text{ V}$ , $1.6\text{ V} \leq \text{V}_b \leq 2.0\text{ V}$ , $\text{C}_b = 30\text{ pF}$ , $\text{R}_b = 5.5\text{ k}\Omega$	958		ns
Slp hold time (from SCKp $\uparrow$ ) <sup>Note</sup>	$t_{\text{KSI}1}$	$4.0\text{ V} \leq \text{EV}_{\text{DD}0} \leq 5.5\text{ V}$ , $2.7\text{ V} \leq \text{V}_b \leq 4.0\text{ V}$ , $\text{C}_b = 30\text{ pF}$ , $\text{R}_b = 1.4\text{ k}\Omega$	38		ns
		$2.7\text{ V} \leq \text{EV}_{\text{DD}0} < 4.0\text{ V}$ , $2.3\text{ V} \leq \text{V}_b \leq 2.7\text{ V}$ , $\text{C}_b = 30\text{ pF}$ , $\text{R}_b = 2.7\text{ k}\Omega$	38		ns
		$2.4\text{ V} \leq \text{EV}_{\text{DD}0} < 3.3\text{ V}$ , $1.6\text{ V} \leq \text{V}_b \leq 2.0\text{ V}$ , $\text{C}_b = 30\text{ pF}$ , $\text{R}_b = 2.7\text{ k}\Omega$	38		ns
Delay time from SCKp $\downarrow$ to SOp output <sup>Note</sup>	$t_{\text{KSO}1}$	$4.0\text{ V} \leq \text{EV}_{\text{DD}0} \leq 5.5\text{ V}$ , $2.7\text{ V} \leq \text{V}_b \leq 4.0\text{ V}$ , $\text{C}_b = 30\text{ pF}$ , $\text{R}_b = 1.4\text{ k}\Omega$		200	ns
		$2.7\text{ V} \leq \text{EV}_{\text{DD}0} < 4.0\text{ V}$ , $2.3\text{ V} \leq \text{V}_b \leq 2.7\text{ V}$ , $\text{C}_b = 30\text{ pF}$ , $\text{R}_b = 2.7\text{ k}\Omega$		390	ns
		$2.4\text{ V} \leq \text{EV}_{\text{DD}0} < 3.3\text{ V}$ , $1.6\text{ V} \leq \text{V}_b \leq 2.0\text{ V}$ , $\text{C}_b = 30\text{ pF}$ , $\text{R}_b = 5.5\text{ k}\Omega$		966	ns

**Note** When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.

**Caution** Select the TTL input buffer for the Slp pin and the N-ch open drain output ( $\text{V}_{\text{DD}}$  tolerance (for the 20- to 52-pin products)/ $\text{EV}_{\text{DD}}$  tolerance (for the 64- to 100-pin products)) mode for the SOp pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg). For  $\text{V}_{\text{IH}}$  and  $\text{V}_{\text{IL}}$ , see the DC characteristics with TTL input buffer selected.

(Remarks are listed on the page after the next page.)

## 3.5.2 Serial interface IICA

(TA = -40 to +105°C, 2.4 V ≤ EVDD0 = EVDD1 ≤ VDD ≤ 5.5 V, VSS = EVSS0 = EVSS1 = 0 V)

Parameter	Symbol	Conditions	HS (high-speed main) Mode				Unit
			Standard Mode		Fast Mode		
			MIN.	MAX.	MIN.	MAX.	
SCLA0 clock frequency	f <sub>SCL</sub>	Fast mode: f <sub>CLK</sub> ≥ 3.5 MHz	–	–	0	400	kHz
		Standard mode: f <sub>CLK</sub> ≥ 1 MHz	0	100	–	–	kHz
Setup time of restart condition	t <sub>SU:STA</sub>		4.7		0.6		μs
Hold time <sup>Note 1</sup>	t <sub>HD:STA</sub>		4.0		0.6		μs
Hold time when SCLA0 = “L”	t <sub>LOW</sub>		4.7		1.3		μs
Hold time when SCLA0 = “H”	t <sub>HIGH</sub>		4.0		0.6		μs
Data setup time (reception)	t <sub>SU:DAT</sub>		250		100		ns
Data hold time (transmission) <sup>Note 2</sup>	t <sub>HD:DAT</sub>		0	3.45	0	0.9	μs
Setup time of stop condition	t <sub>SU:STO</sub>		4.0		0.6		μs
Bus-free time	t <sub>BUF</sub>		4.7		1.3		μs

**Notes** 1. The first clock pulse is generated after this period when the start/restart condition is detected.

<R> 2. The maximum value (MAX.) of tHD:DAT is during normal transfer and a wait state is inserted in the ACK (acknowledge) timing.

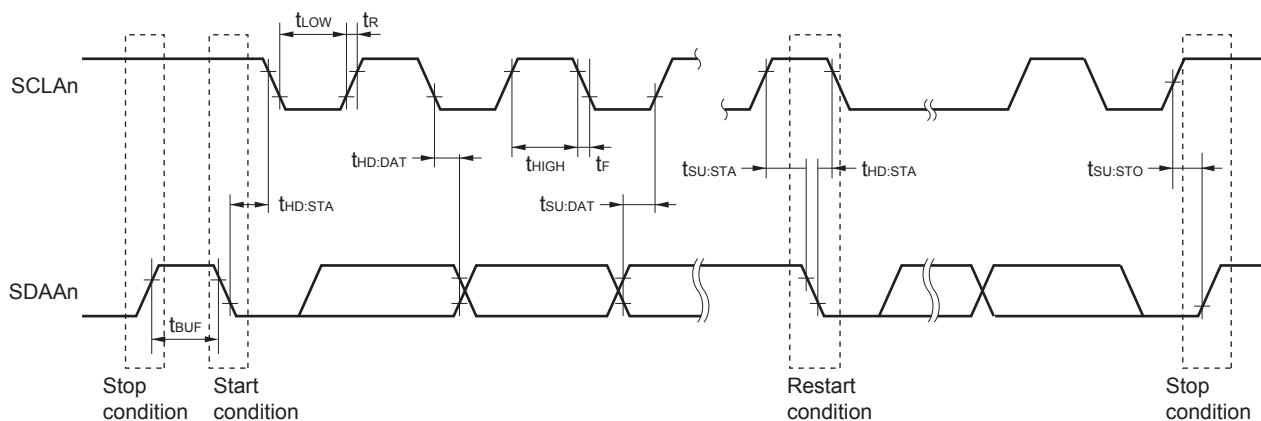
**Caution** The values in the above table are applied even when bit 2 (PIOR2) in the peripheral I/O redirection register (PIOR) is 1. At this time, the pin characteristics (IOH1, IOL1, VOH1, VOL1) must satisfy the values in the redirect destination.

**Remark** The maximum value of Cb (communication line capacitance) and the value of Rb (communication line pull-up resistor) at that time in each mode are as follows.

Standard mode: Cb = 400 pF, Rb = 2.7 kΩ

Fast mode: Cb = 320 pF, Rb = 1.1 kΩ

IICA serial transfer timing

**Remark** n = 0, 1

### 3.6 Analog Characteristics

#### 3.6.1 A/D converter characteristics

Classification of A/D converter characteristics

Input channel	Reference Voltage		
	Reference voltage (+) = $AV_{REFP}$ Reference voltage (-) = $AV_{REFM}$	Reference voltage (+) = $V_{DD}$ Reference voltage (-) = $V_{SS}$	Reference voltage (+) = $V_{BGR}$ Reference voltage (-) = $AV_{REFM}$
ANI0 to ANI14	Refer to 3.6.1 (1).	Refer to 3.6.1 (3).	Refer to 3.6.1 (4).
ANI16 to ANI26	Refer to 3.6.1 (2).		
Internal reference voltage Temperature sensor output voltage	Refer to 3.6.1 (1).		—

(1) When reference voltage (+) =  $AV_{REFP}/ANI0$  ( $ADREFP1 = 0$ ,  $ADREFP0 = 1$ ), reference voltage (-) =  $AV_{REFM}/ANI1$  ( $ADREFM = 1$ ), target pin : ANI2 to ANI14, internal reference voltage, and temperature sensor output voltage

( $T_A = -40$  to  $+105^\circ\text{C}$ ,  $2.4\text{ V} \leq AV_{REFP} \leq V_{DD} \leq 5.5\text{ V}$ ,  $V_{SS} = 0\text{ V}$ , Reference voltage (+) =  $AV_{REFP}$ , Reference voltage (-) =  $AV_{REFM} = 0\text{ V}$ )

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Resolution	RES		8		10	bit
Overall error <sup>Note 1</sup>	AINL	10-bit resolution $AV_{REFP} = V_{DD}$ <sup>Note 3</sup>	$2.4\text{ V} \leq AV_{REFP} \leq 5.5\text{ V}$	1.2	$\pm 3.5$	LSB
Conversion time	$t_{CONV}$	10-bit resolution Target pin: ANI2 to ANI14	$3.6\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	2.125	39	$\mu\text{s}$
			$2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	3.1875	39	$\mu\text{s}$
			$2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	17	39	$\mu\text{s}$
		10-bit resolution Target pin: Internal reference voltage, and temperature sensor output voltage (HS (high-speed main) mode)	$3.6\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	2.375	39	$\mu\text{s}$
			$2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	3.5625	39	$\mu\text{s}$
			$2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	17	39	$\mu\text{s}$
Zero-scale error <sup>Notes 1, 2</sup>	$E_{ZS}$	10-bit resolution $AV_{REFP} = V_{DD}$ <sup>Note 3</sup>	$2.4\text{ V} \leq AV_{REFP} \leq 5.5\text{ V}$		$\pm 0.25$	%FSR
Full-scale error <sup>Notes 1, 2</sup>	$E_{FS}$	10-bit resolution $AV_{REFP} = V_{DD}$ <sup>Note 3</sup>	$2.4\text{ V} \leq AV_{REFP} \leq 5.5\text{ V}$		$\pm 0.25$	%FSR
Integral linearity error <sup>Note 1</sup>	ILE	10-bit resolution $AV_{REFP} = V_{DD}$ <sup>Note 3</sup>	$2.4\text{ V} \leq AV_{REFP} \leq 5.5\text{ V}$		$\pm 2.5$	LSB
Differential linearity error <sup>Note 1</sup>	DLE	10-bit resolution $AV_{REFP} = V_{DD}$ <sup>Note 3</sup>	$2.4\text{ V} \leq AV_{REFP} \leq 5.5\text{ V}$		$\pm 1.5$	LSB
Analog input voltage	$V_{AIN}$	ANI2 to ANI14	0		$AV_{REFP}$	V
		Internal reference voltage output ( $2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$ , HS (high-speed main) mode)	$V_{BGR}$ <sup>Note 4</sup>			V
		Temperature sensor output voltage ( $2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$ , HS (high-speed main) mode)	$V_{TMPS25}$ <sup>Note 4</sup>			V

(Notes are listed on the next page.)